RECORDA

102081207

J.S. Department of Commerce Patent and Trademark Office

_			OHL:	PA	IENI		
TO: The Commis	sioner of Patents and	Trademarks: Please	record the attached	original document(s) or copy(ies).		
Submission Typ	е		Conveyance Type	•	PT 919		
New New					"Si		
	n (Non-Recordation)		License		³ 0971 ^{U.S.}		
Document ID	#		☐ Merger		<u> </u>		
☐ Correction of	PTO Error	5-1-02	Security Agree	ment	7		
Reel #	Frame #	2-1-0-	☐ Change of Nam	ne	152		
☐ Corrective Do	cument		Other:		ΰ		
Reel #	Frame #				' '		
Conveying Party	(ies)			Execution Date(s	s)		
1. Chigusa YASUDA				April 15, 2002			
2. Akira HAMAS				April 15, 2002			
3.							
4.							
5.							
6.							
Mark if Addition	onal Names of Conve	ying Parties Attache	d				
Receiving Party							
Name	MITSUBISHI DENKI	KABUSHIKI KAISH	Ą				
Name							
Address	2-3, Marunouchi 2-ch	home, Chiyoda-ku					
Address							
Address	<u>Tokyo</u>	<u>Japan</u>		<u>100-8310</u>			
	City	State/Cou		Zip Code			
	onal Names of Fleceiv	ing Parties Attached					
Correspondent I	Name and Address						
				T.1	- (000) 707 0770		
Jeffrey A. Wyand			Telephone: (202) 737-6770				
Leydig, Voit & Ma	yer, Ltd.		Facsimile: (202) 737-6776 Attorney Docket No. 401682/Asahina				
700 Thirteenth St				Attorney Docket No	o. 401682/Asanina		
Washington, D.C							
	the total number of p		conveyance docum				
Application Num	ber(s) or Paterit Nur	mber(s)		Mark if additional n			
	Patent Application Number ent Application Num			Patent Numbers	erty).		
10 12 e 11.	A Application Num	ibers		i atom Hambers			
10/133 41	7						
			•				
If their also access and i	s being filed together	with a pau Datant A	nlication antar tha	data the patent	Month Day Year		
				date the patent	April 15, 2002		
	igned by the first nam ion Treaty (PCT)	ed executing invente	1.		April 13, 2002		
		II C Application	PCT	PCT	PCT		
Number has not b	ation number <i>only if</i> a	U.S. Application	101	1 01	101		
Number has not t	been assigned.		PCT	PCT	PCT		
			1 0 1	1 0 1	' ' '		
Number of Prop	ortice		Enter the t	otal number of prop	erties involved: 1		
	er des		Litter the t	otal Hamber of prop	critico involved.		
Fee Amount			Fee Amount for Pr	onartias Listad (37 (CER 3.41): 40.00		
Fee Amount for Properties Listed (37 CFR 3.41): 40.00 Method of Payment:							
		ount of \$780.00					
☑ Enclosed is a check in the amount of \$780.00☐ Charge Deposit Account No. 12-1216							
Authorization to Charge Additional Fees to Deposit Account No. 12-1216: Yes No							
Statement and Signature							
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a							
true copy of the original document. Charges to deposit account are authorized, as indicated herein.							
Jeffrey A. Wyand Agu Wyaud May 2002							
Name of Person Signing // Signature / Date							
		-	V				

PATENT

REEL: 012858 FRAME: 0315

RECORDATION FORM COVER SHEET				
CONTINUATION				
PATENTS ONLY				

U.S. Department of Commerce Patent and Trademark Office PATENT

Attorney Docket No.401682

Conveying Part 7. 8. 9. 10. 11.	y(ies)			Execution Dat	e(s)		
Receiving Party	v(ies)						
Name	RYODEN SEMICONDUCTOR SYSTEM ENGINEERING CORPORATION						
Name Address Address Address	1, Mizuhara 4-chomo Itami-shi City	<u>Hyogo-ke</u> State/Cou		Zip Code			
Name Name Address Address Address	City	State/Cou	mtn.	Zin Codo			
City State/Country Zip Code Application Number(s) or Patent Number(s)							
Patent Application Numbers				Patent Number	<u>s</u>		
10,13541	7						
If this document is being filed together with a <i>new</i> Patent Application, enter the date the patent application was signed by the first named executing inventor. Month Day Year April 15, 2002							
	tion Treaty (PCT) cation number only if a been assigned.	U.S. Application	PCT	PCT	PCT		

Assignment Tml P2

PATENT REEL: 012858 FRAME: 0316

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned,

Chigusa Yasuda and Akira Hamasaki

- of c/o RYODEN SEMICONDUCTOR SYSTEM ENGINEERING CORPORATION, 1, Mizuhara 4-chome, Itami-shi, Hyogo-ken, Japan
- hereby sells, assigns and transfers to
 MITSUBISHI DENKI KABUSHIKI KAISHA and
 RYODEN SEMICONDUCTOR SYSTEM ENGINEERING CORPORATION
- of 2-3, Marunouchi 2-chome, Chiyoda-ku, Tokyo 100-8310 Japan and 1, Mizuhara 4-chome, Itami-shi, Hyogo-ken, Japan, respectively

(hereinafter called the Assignee), its successors and assigns, the entire right, title, and interest in and to:

- (i) the application for United States Letters Patent entitled:

 METHOD FOR PREPARING MANUFACTURING PLAN AND METHOD FOR
 MANUFACTURING SEMICONDUCTOR PRODUCTS USING THE MANUFACTURING PLAN

 which was executed by the undersigned on

 April 15 _______ or was filed on

 and accorded Serial

 No. ______ (hereinafter called the Application);
- (ii) any and all inventions and improvements which are described in the Application;
- (iii) any and all United States Letters Patents which may be granted on the Application (hereinafter called the Patent);
- (iv) any and all divisions, continuations, substitutes, reexaminations, reissues, or extensions of the Application or Patent; and
- (v) all benefits under the International Convention for the Protection of Industrial Property.

The Assignee and its agents are hereby authorized to insert in this instrument the filing date and serial number of said application.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

PATENT REEL: 012858 FRAME: 0317

ings, including reexamination assistance requested by the Amappropriate patent protection	papers; and provide all reasonable ssignee to secure and maintain.
Signed at Hyogo, Japan	
this 15th day of April	
WITNESS(ES):	INVENTOR(S):
Hiroshi Kamide	Chiquea Yasuda
Toyoharu Shimuda	Akira Hamasaki

RECORDED: 05/01/2002

Further, it is agreed that, when requested, without charge

to but at the expense of said Assignee, the undersigned will

execute all divisional, continuing, substitute, or reissue patent applications; execute all additional assignments and other writ-

PATENT REEL: 012858 FRAME: 0318